ABSTRACT

Provided is an electroplating chuck for a square substrate, comprising: a substrate chuck plate, provided with an inner edge for supporting the substrate; a pressing plate, disposed above the substrate chuck plate, wherein a guide post is arranged between the substrate chuck plate and the pressing plate, the pressing plate can ascend or descend along the guide post, the bottom of the pressing plate is provided with a first reinforcing rib configured to contact the edge of the substrate when the pressing plate presses the substrate, and the first reinforcing rib is square-shaped and the inner side length of the first reinforcing rib is less than the side length of the substrate; at least one suction member, fixed on the pressing plate, for adsorbing the substrate. The present invention effectively solves the warpage problem of large-size square substrate products, significantly improves the electroplating uniformity of the square substrate, reliably guarantees product quality and the yield rate of continuous production, and features a simple structure and low production cost.